

Disco DFG841

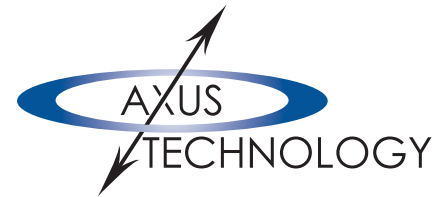


Disco DFG841 system, with two grind spindles, two wafer vacuum chucks, and a robot arm, features a same-cassette return function. The robot arm vacuum feature ensures that even thin-ground wafers, which are prone to warping, are corrected to the required flatness for trouble-free handling. For safety, the DFG841 complies with the EC's CE marking and is based on SEMI S2-93.

OPTIONS AVAILABLE

Temperature control system for stabilizing process results

Vacuum system



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FEATURES

- Grinds wafers 100 - 200mm
- In-feed grinding with wafer rotation
- Two independently adjustable spindles
- Porous chuck table with vacuum chuck
- 200mm diamond grinding wheel
- 2 cassettes for load/unload
- DFG841 complies with the EC's CE requirements